10 Reflow Profile

The reflow profile recommended in this document is a lead-free reflow profile that is suitable for pure lead-free technology of lead-free solder paste. Figure 10-1 shows the typical reflow profile of AXP323 device sample.

Figure 10-1 AXP323 typical reflow profile

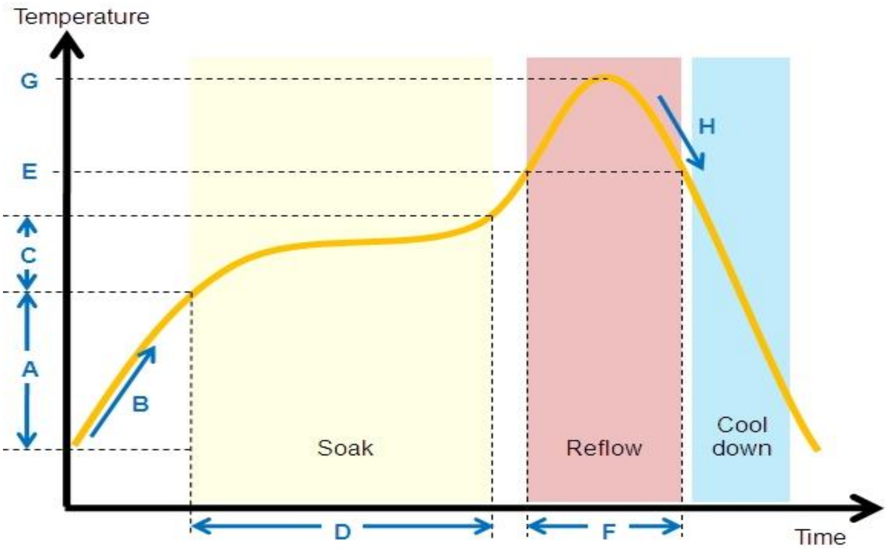

Table 10-1 AXP323 Reflow Profile Conditions

	QTI typical SMT reflow profile conditions (for reference only)	
	Step	Reflow condition
Environment	N2 purge reflow usage (yes/no)	Yes, N2 purge used
	If yes, O2 ppm level	O2 < 1500 ppm
A	Preheat ramp up temperature range	25°C -> 150°C
B	Preheat ramp up rate	1.5~2.5 °C/sec
C	Soak temperature range	150°C -> 190°C
D	Soak time	80~110 sec
E	Liquidus temperature	217°C
F	Time above liquidus	60-90 sec
G	Peak temperature	240-250°C
H	Cool down temperature rate	≤4°C/sec